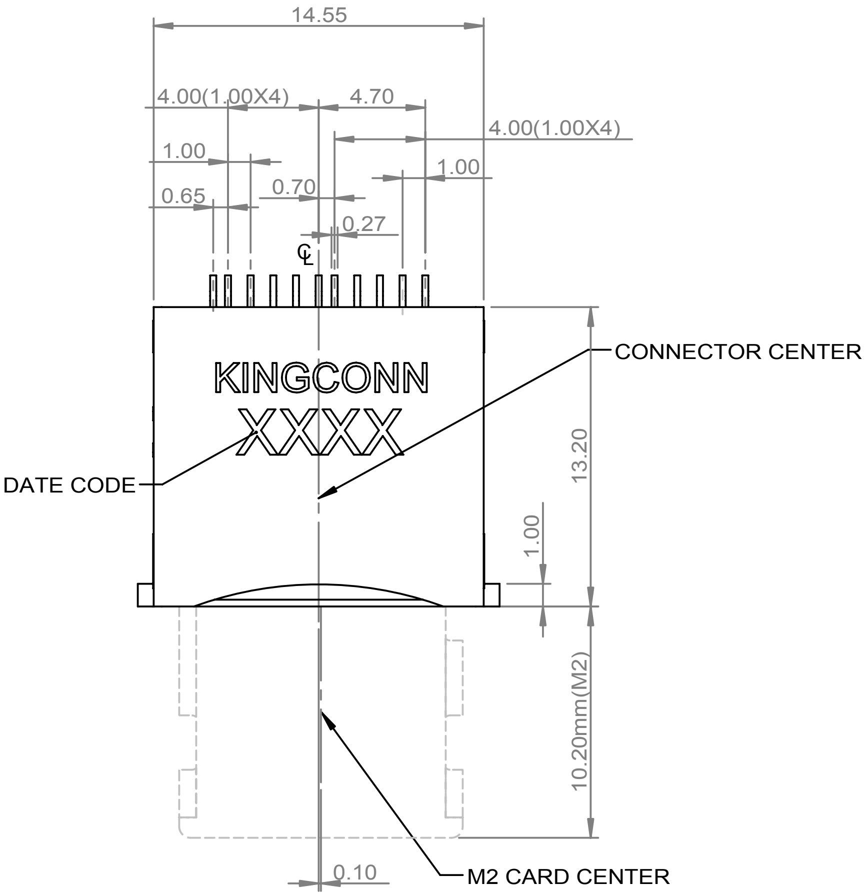
更改 REV	設 變 內 容 MODIFICATION
A	ECN01863
B	ECN02001
C	ECN02343
D	ECN02817
E	ECN03185
F	ECN03434

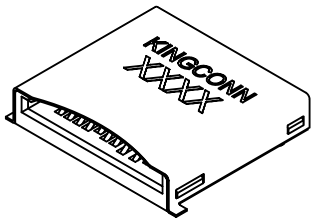


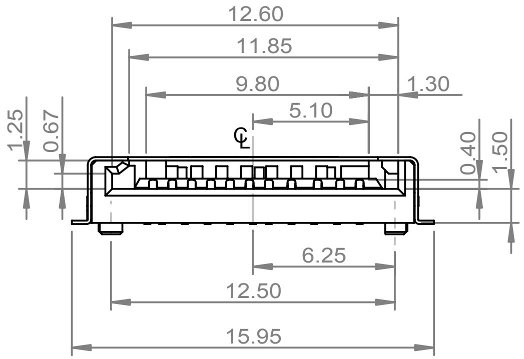
NOTES:
1. MATERIAL:
   INSULATOR: HIGH TEMPRATURE THERMOPLASTIC,
   UL94V-0,BLACK
   CONTACT: PHOSPHOR BRONZE
2. PART NO:7SDM2-X0-X0X1

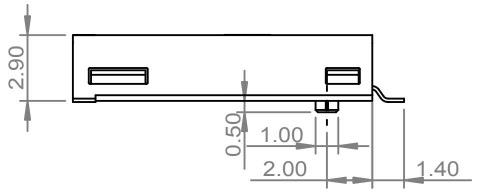
LOGO: F
0:有LOGO
1:無LOGO

PACKING:
0 :TRAY
1 :TAPE&REEL

PLATING:
F: CONTACT AREA:GOLD FLASH Au PLATED OVER Ni
   SOLDER AREA:MATTE Tin PLATED OVER Ni
B: CONTACT AREA:10μ" Au PLATED OVER Ni
   SOLDER AREA:MATTE Tin PLATED OVER Ni







GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°

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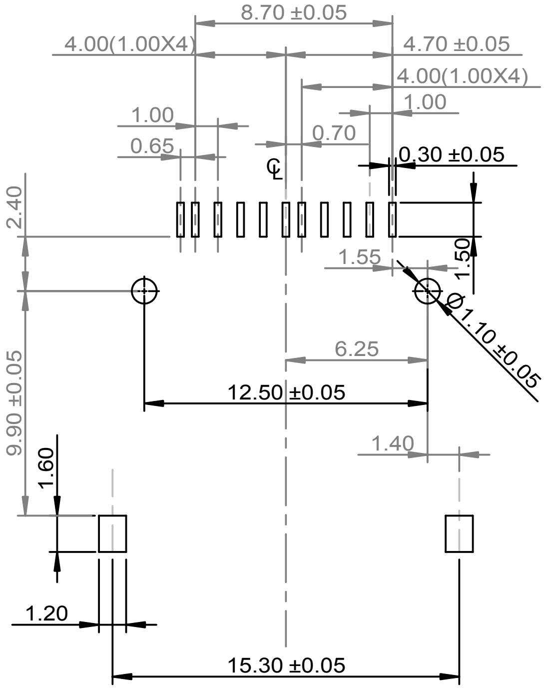
名 稱(TITLE)
Memory Stick micro CONNECTOR

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	7SDM2-X0-X0X1	7SDM2-X0-X0X1-F

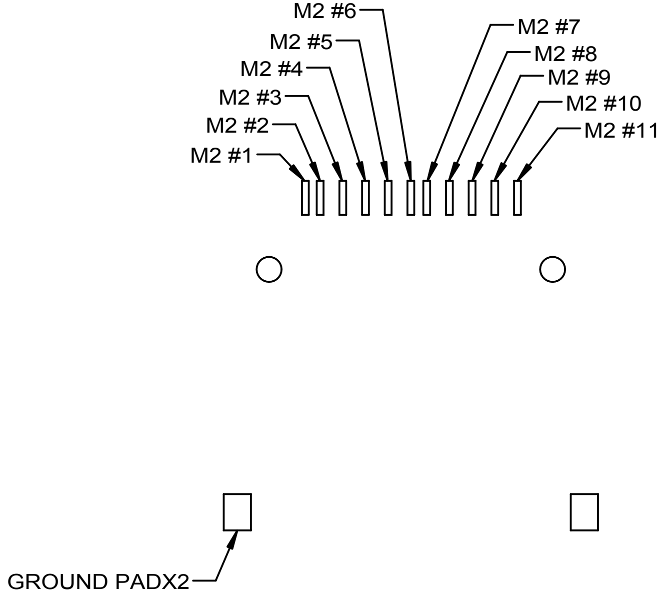
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE	3:1	張 數 SHEET	1/2
			角 法 PROJ.		更 改 REV	F

RoHS

更改 REV	設 變 內 容 MODIFICATION
A	ECN01863
B	ECN02001
C	ECN02343
D	ECN02817
E	ECN03185
F	ECN03434



PCB LAYOUT



Pin Assignment

M2 #1	BS
M2 #2	DAT1
M2 #3	DAT0
M2 #4	DAT2
M2 #5	INS
M2 #6	DAT3
M2 #7	SCLK
M2 #8	VCC
M2 #9	VSS
M2#10	NC/Roscrved
M2#11	NC/Roscrved

GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°

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名 稱(TITLE)	Memory Stick micro CONNECTOR	
單 位(UNIT) mm	料 號(PART NO.) 7SDM2-X0-X0X1	圖 號(DWG NO.) 7SDM2-X0-X0X1-F
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)
比 例 SCALE 3:1	張 數 SHEET 2/2	
角 法 PROJ.	更 改 REV F	